

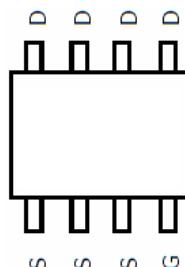
40V(D-S) N-Channel Enhancement Mode Power MOS FET

General Features

- $V_{DS} = 40V, I_D = 12A$
- $R_{DS(ON)} < 12m\Omega @ V_{GS}=10V$ (Typ. $8.4 m\Omega$)
- $R_{DS(ON)} < 18m\Omega @ V_{GS}=4.5V$ (Typ. $12.3 m\Omega$)
- High density cell design for ultra low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability



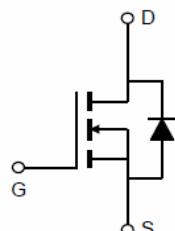
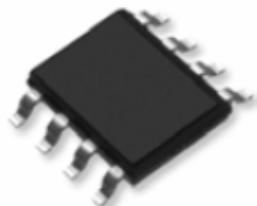
Lead Free



Marking and pin Assignment

Application

- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

PIN Configuration

Schematic diagram

SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MSN0412W	MSN0412W	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	12	A
Drain Current-Continuous($T_C=100^\circ C$)	$I_D (100^\circ C)$	8.5	A
Pulsed Drain Current	I_{DM}	60	A
Maximum Power Dissipation	P_D	3	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

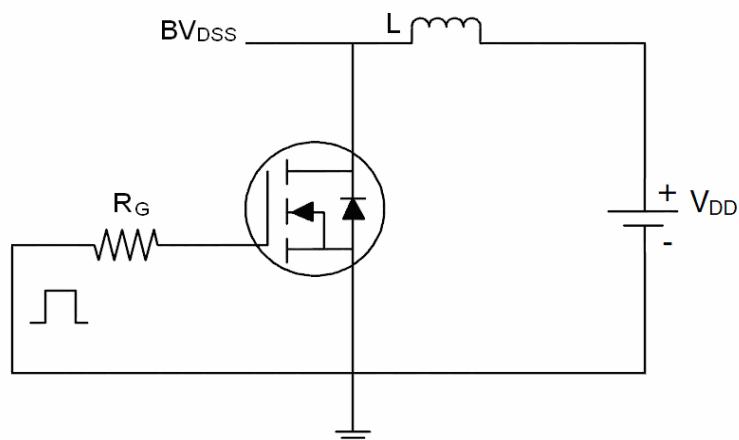
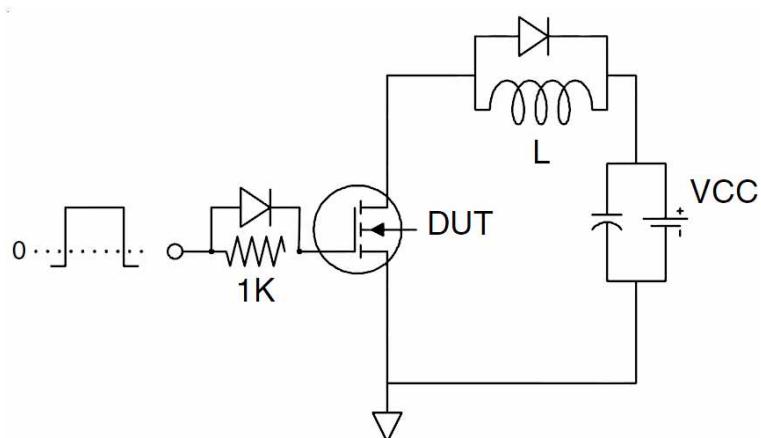
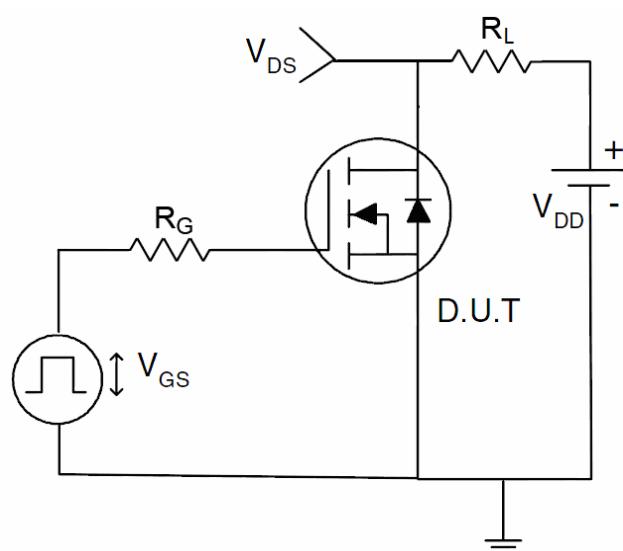
Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	41.7	°C/W
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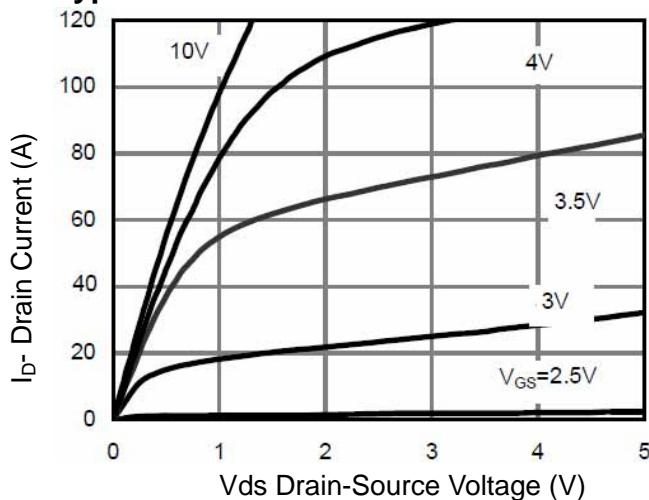
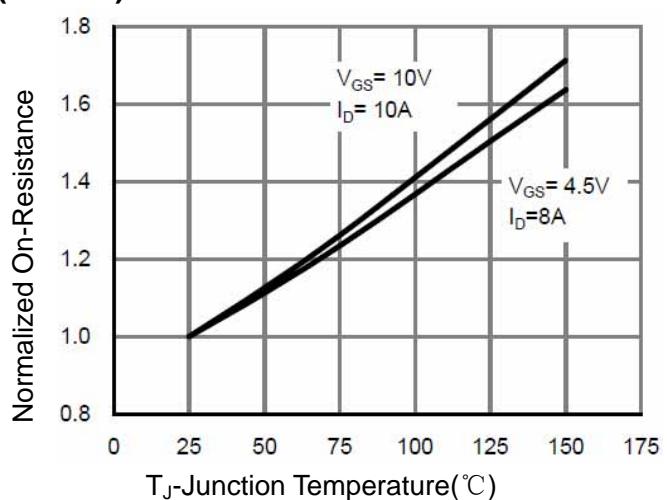
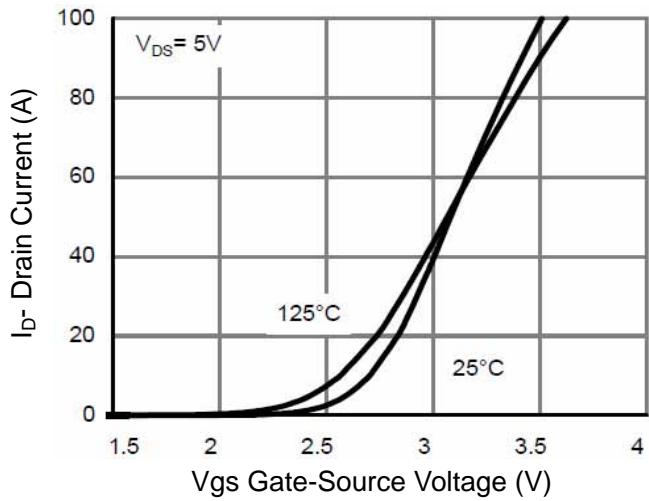
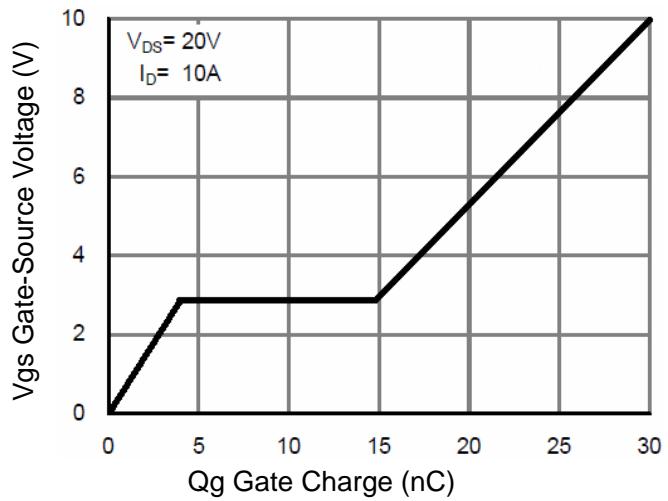
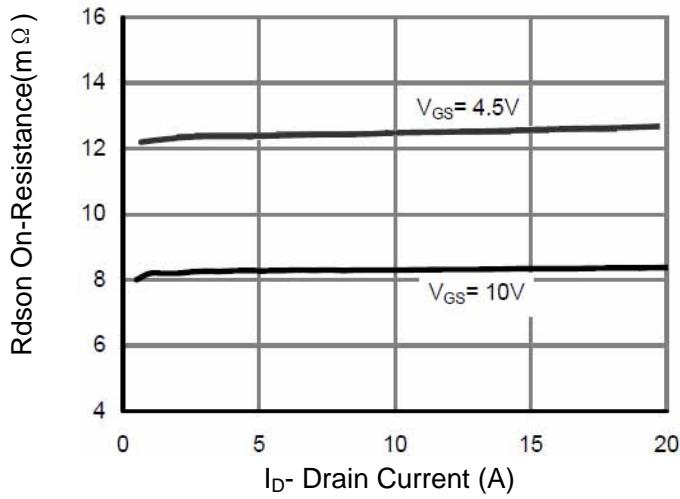
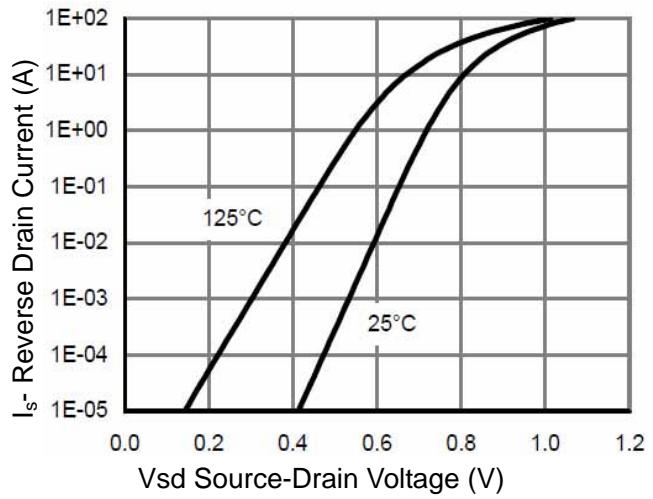
Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

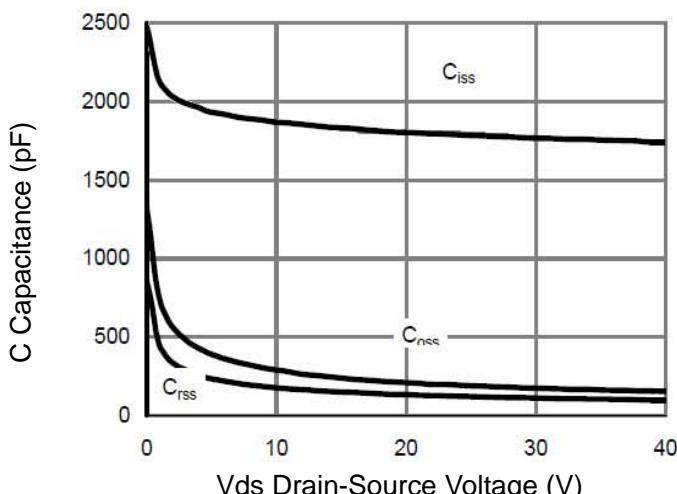
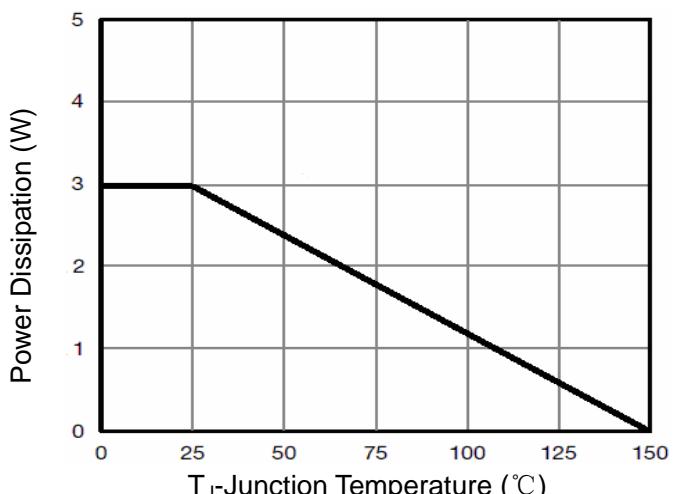
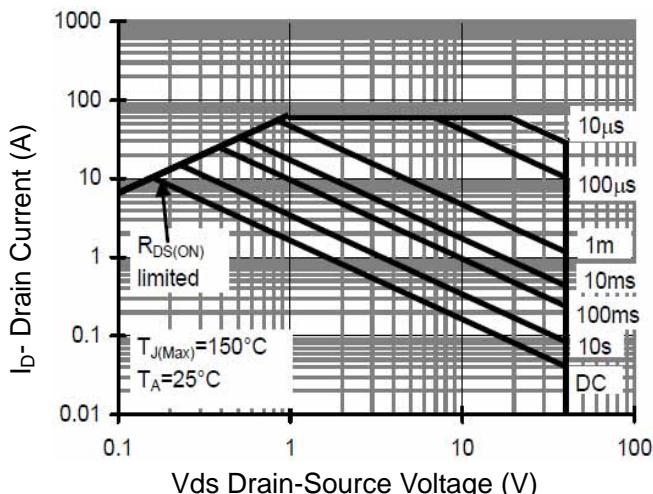
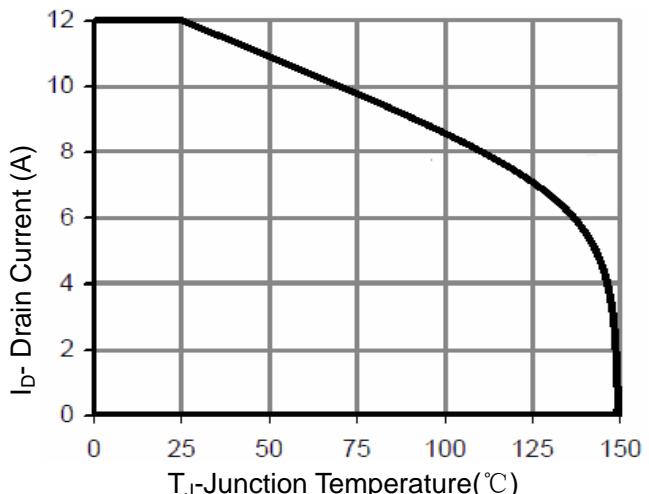
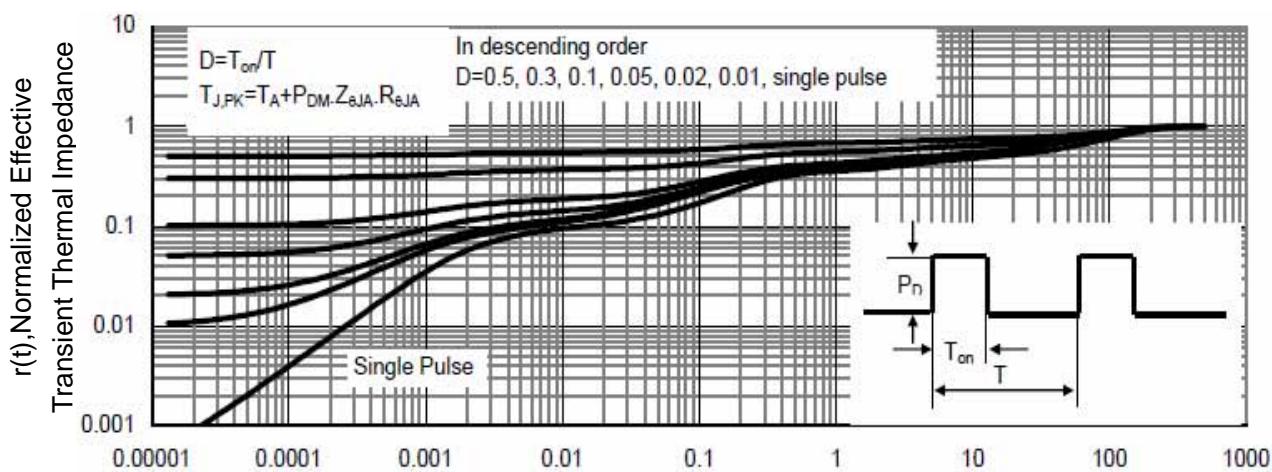
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	45	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.6	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$	-	8.4	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=8\text{A}$	-	12.3	18	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=10\text{A}$		75	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	1780	-	PF
Output Capacitance	C_{oss}		-	209	-	PF
Reverse Transfer Capacitance	C_{rss}		-	160	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=20\text{V}, R_{\text{L}}=2\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=3\Omega$	-	6.4	-	nS
Turn-on Rise Time	t_{r}		-	17.2	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	29.6	-	nS
Turn-Off Fall Time	t_{f}		-	16.8	-	nS
Total Gate Charge	Q_{g}	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=10\text{A}, V_{\text{GS}}=10\text{V}$	-	30	-	nC
Gate-Source Charge	Q_{gs}		-	4.2	-	nC
Gate-Drain Charge	Q_{gd}		-	9.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=10\text{A}$	-		1.2	V
Diode Forward Current ^(Note 2)	I_{S}		-	-	12	A
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, IF = 10\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ ^(Note 3)	-	29	-	nS
Reverse Recovery Charge	Q_{rr}		-	26	-	nC

Notes:

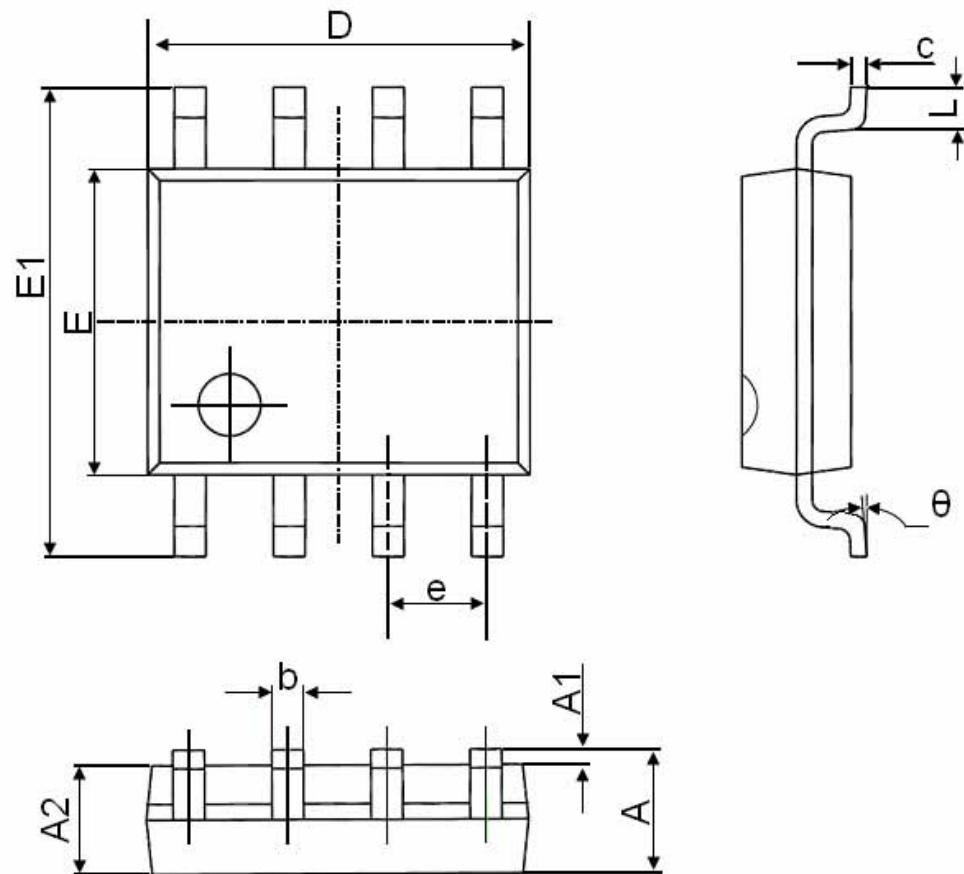
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Test circuit**1) E_{AS} Test Circuit****2) Gate Charge Test Circuit****3) Switch Time Test Circuit**

Typical Electrical and Thermal Characteristics (Curves)**Figure 1 Output Characteristics****Figure 4 Rdson-JunctionTemperature****Figure 2 Transfer Characteristics****Figure 5 Gate Charge****Figure 3 Rdson- Drain Current****Figure 6 Source- Drain Diode Forward**

**Figure 7 Capacitance vs Vds****Figure 9 Power De-rating****Figure 8 Safe Operation Area****Figure 10 Current De-rating****Figure 11 Normalized Maximum Transient Thermal Impedance**

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°		8°	